

Final Announcement

**13th INTERNATIONAL SEMINAR
ON POWER SEMICONDUCTORS**

ISPS'16

Organised by the IET Czech Local Network in co-operation with
the IEEE Czechoslovakia Section and
Faculty of Electrical Engineering
(Department of Electrotechnology)
Czech Technical University in Prague

Prague, 31 August – 2 September 2016

AREAS OF INTEREST:

-power semiconductor devices (materials, physics, modelling, technology, diagnostics)

-advanced device applications, reliability and diagnostics.

28 papers (6 invited papers, 13 regular papers for oral presentation and 9 papers for poster presentation) oriented in the field of power semiconductors will be presented.

INVITED PAPERS

The Substrate requirements for the next generation power electronics

Shin-Ichi Nishizawa

Reverse recovery of diamond pin diodes

Aboulye Traore, Akira Nakajima, et al,

Overcoming Switching Limits in Silicon Power MOSFETs with Silicon-Based Solutions

Jaume Roig, Frederick Declercq and Filip Bauwens

Monolithically-Integrated Power Circuits in a High-Voltage GaN-on-Si Heterojunction Technology

Richard Reiner

IGBT-based device- and packaging technologies for future high power applications

Arnost Kopta, Munaf Rahimo,, et al,

IGBTs: Recent developments and future perspectives Invited

Franz-Josef Niedernostheide, Hans-Joachim Schulze and Thomas Laska

Presented papers will be published in the Seminar proceedings, which will be distributed at the Seminar registration. Papers presented may be selected for possible inclusion in special issues of refereed journals.

RELATED SCIENTIFIC EVENT:

The technical programme of the ISPS'16 will be round by two **Tutorials**

Carlo De Santi, Gaudenzio Meneghesso, Matteo Meneghini and Enrico Zanoni:
“Dynamic effects and reliability of depletion and enhancement GaN HEMTs for power switching applications“

Mikael Östling: **“Silicon Carbide Power Device Technology; Fabrication issues and state of the art devices”**

The **Tutorials** will take place **on 31 August, 2016** in the morning.

Additional fee (for the ISPS'16 participants) of 20 EUR include refreshments and the short course materials.

WORKING LANGUAGE: The working language on the ISPS'16 Conference is English. It will be used in the printed material, presentations and discussion.

INTERNATIONAL PROGRAMME COMMITTEE

Chairman:

Prof. Sankara N. Ekkanath Madathil, University of Sheffield, UK

Co-chairmen:

Prof. Josef Lutz, Chemnitz University of Technology, GER

Prof. Pavel Hazdra, Czech Technical University in Prague, CZ

Members:

Prof. Vítězslav Benda, Czech Technical University in Prague, CZ

Prof. Merlyne De Souza, University of Sheffield, UK

Dr. David Flores, CNM-CSIC Barcelona, ESP

Masayasu Ishiko, Toyota Central R&D Labs, JPN

Prof. Nando Kaminski, University of Bremen, GER

Prof. Zbygniew Lisik, University of Lodz, POL

Dr.- Ing. habil. Reinhard Herzer, GER

Prof. Wai Tung Ng, University of Toronto, CAN

Dr. Vaclav Papez, Czech Technical University in Prague, CZ

Dr. Sameer Pendharkar, Texas Instruments, USA

Dr. Hans-Joachim Schulze, Infineon, GER

Prof. Siegfried Selberherr, TU Wien, AUT

Prof. Ninoslav Stojadinovic, University of Nis, SRB

Prof. Jan Vobecky, ABB, SUI

Prof. Gerhard Wachutka, Munich University of Technology, GER

Prof. John Shen, Illinois Institute of Technology, USA

Dr. Ritu Sodhi, Empower Semiconductor, INDIA

Dr. David Green, SILVACO, UK

Prof. Bo Zhang, UESTC, China

Prof. Heinrich Schlangenotto, GER

Dr. Munaf Rahimo, ABB, Switzerland

Dr. W. Saito, Toshiba, Japan

Prof. Andrea Irace, University of Napoli, Italy

ORGANISING COMMITTEE:

Chairman: Prof. Vitezslav Benda, PhD, FIET

Members: Petr Cesak, MSc

Dr. Karel Kuenzel

Dr. Martin Molhanec

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ISPS'16 Organising Committee

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email: benda@fel.cvut.cz

<http://technology.feld.cvut.cz/ISPS2016>

CONFERENCE LOCATION

The conference will take place at the Faculty of Electrical Engineering of the CTU in Prague, Technická 2, Prague 6

REGISTRATION FEE:

IET and IEEE members: EUR 270

Non-members EUR 300

(Students can apply for a 20% discount – application and payment must be received by July 31, 2016)

The registration fee will cover the cost of the seminar, documentation, proceedings, refreshments and social programme. Registration is possible before 15 August 2016.

Accompanying persons EUR 70 (full social programme)

Proceedings (extra copy) EUR 25

Payment should be made in EUR or in an equivalent amount in other convertible currency by bank remittance to the bank:

CESKA SPORITELNA a.s., Dejvická 50, 160 00 Praha 6, Czech Republic
(SWIFT: GIBACZPX), account No.: **19-164913359/0800**

IBAN: CZ97 0800 0000 1901 6491 3359

Payment can be also done in cash at the conference desk.

In this case on-site registration fees apply EUR 320.

Please send fulfilled registration form to the ISPS'10 Organising Committee, no later than **15 August, 2016**.

Social Programme

ISPS'14 Welcome Party on 31 August, 2016

ISPS'14 Social Dinner on 1 September, 2016

Prague Excursion on 28 August, 2016

INSURANCE

The organisers cannot be held responsible for accidents to ISPS'16 attendants or for damage to, or loss of their personal property, howsoever caused. Attendants should therefore make their own insurance arrangements.

ISPS'16 REGISTRATION FORM

Surname.....
First Name.....
Title.....
Organisation.....
Address.....
Phone.....
Fax.....
e-mail.....

I am going to attend the ISPS'16

Accompany person:

I am going to attend the Tutorials

yes

no

I will pay registration fee

IET/IEEE Membership No.:

 accompanying person's fee

 Proceedings extra copy

 Tutorials

 Total

The payment will be realised by a bank transfer

yes/no

I will pay the registration fee at registration

yes/no

Date

Signature